

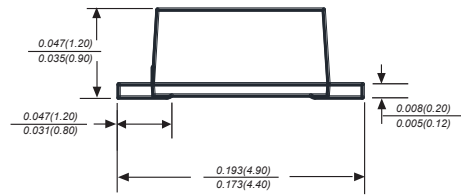
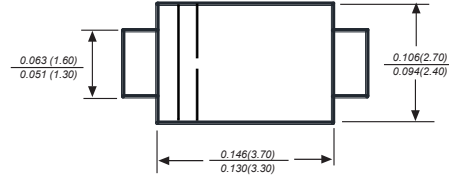


LOW FORWARD VOLTAGE SCHOTTKY BARRIER DIODES

Features

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SMAF



Dimensions in inches and (millimeters)

Mechanical Data

- Case: UT Ø molded plastic body
- Terminals: Solderable per MIL-STD-750, Method 2026A
- Polarity: Polarity symbol marking on body
- Mounting Position: Any
- Weight: 0.00€J ounce, 0.0G7 grams

Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	SL54F	UNITS
Marking Code		MDD SL54F	
Maximum repetitive peak reverse voltage	V <sub>RRM</sub>	40	V
Maximum RMS voltage	V <sub>RMS</sub>	28	V
Maximum DC blocking voltage	V <sub>DC</sub>	40	V
Maximum average forward rectified current at TL (see fig.1)	I <sub>(AV)</sub>	5.0	A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I <sub>FSM</sub>	150	A
Maximum instantaneous forward voltage at 5.0A	V <sub>F</sub>	0.45	V
Maximum DC reverse current T <sub>A</sub> =25°C at rated DC blocking voltage T <sub>A</sub> =125°C	I <sub>R</sub>	1.0 50	mA
Typical junction capacitance (NOTE 1)	C <sub>J</sub>	800	pF
Typical thermal resistance (NOTE 2)	R <sub>θJA</sub>	45.0	°C/W
Operating junction temperature range	T <sub>J</sub>	-55 to +150	°C
Storage temperature range	T <sub>STG</sub>	-55 to +150	°C

- Note: 1. Measured at 1.0MHz and applied reverse voltage of 4.0V D.C.
- 2. P.C.B. mounted with 2.0x2.0" (5.0x5.0cm) copper pad areas
- 3. The typical data above is for reference only.

## Typical Characteristics

Fig.1 Forward Current Derating Curve

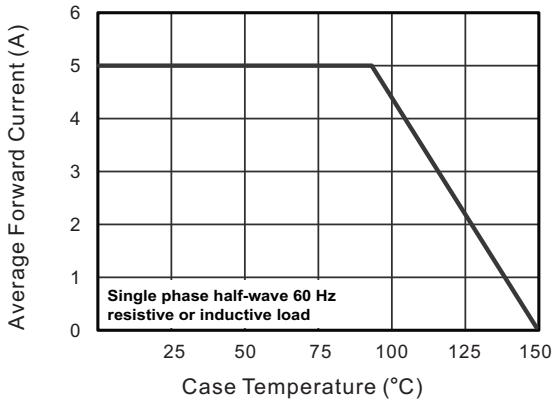


Fig.2 Typical Reverse Characteristics

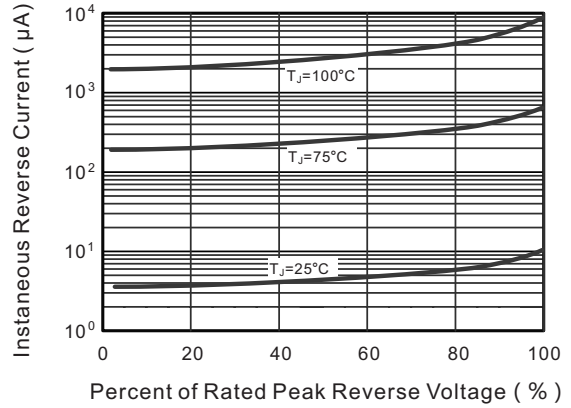


Fig.3 Typical Forward Characteristic

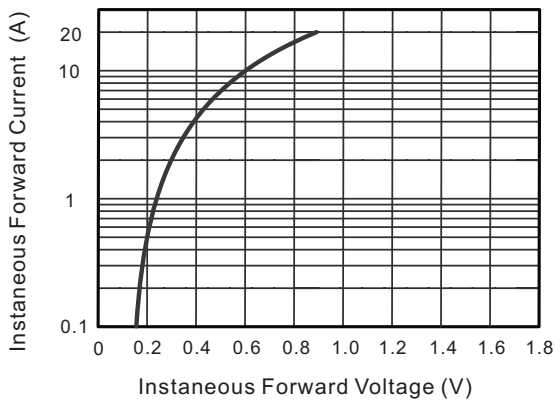


Fig.4 Typical Junction Capacitance

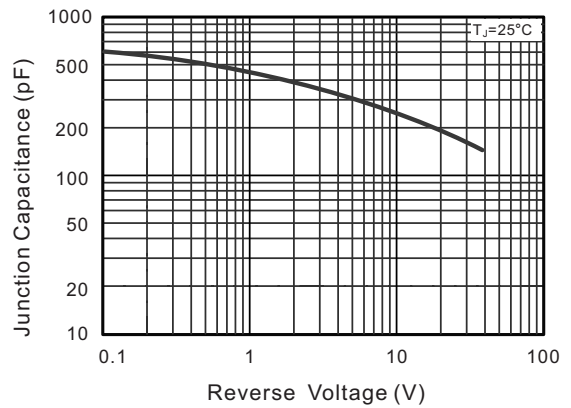


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

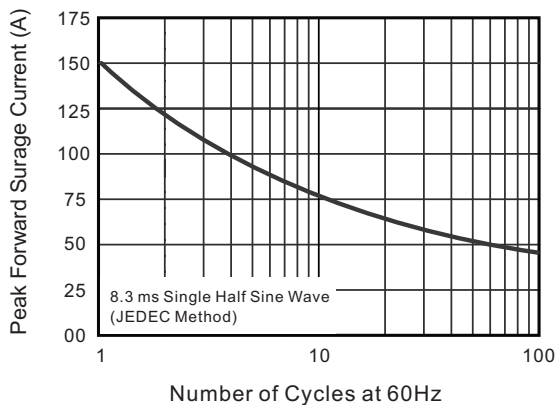
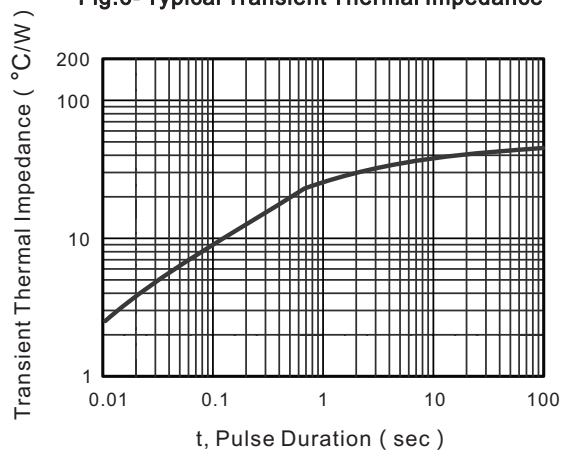
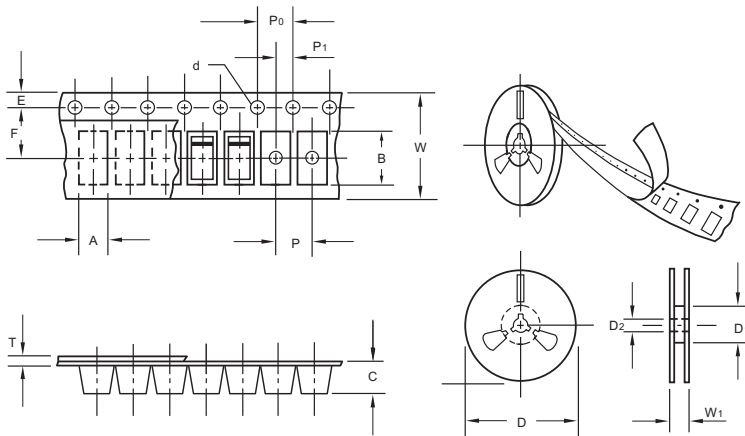


Fig.6- Typical Transient Thermal Impedance



The curve above is for reference only.

## Packing information



unit:mm

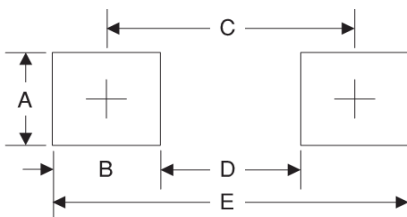
Item	Symbol	Tolerance	SMAF
Carrier width	A	0.1	2.80
Carrier length	B	0.1	4.75
Carrier depth	C	0.1	1.42
Sprocket hole	d	0.05	1.50
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D <sub>1</sub>	min	54.40
Feed hole diameter	D <sub>2</sub>	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	5.05
Punch hole pitch	P	0.1	4.00
Sprocket hole pitch	P <sub>0</sub>	0.1	4.00
Embossment center	P <sub>1</sub>	0.1	2.00
Overall tape thickness	T	0.1	0.30
Tape width	W	0.3	8.00
Reel width	W <sub>1</sub>	1.0	12.30

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

## Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SMAF	7"	3,000	4.0	6,000	210*208*203	178	400*265*400	120,000	10.0

## Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
A	1.8	0.071
B	1.6	0.063
C	3.8	0.150
D	2.2	0.087
E	5.4	0.213